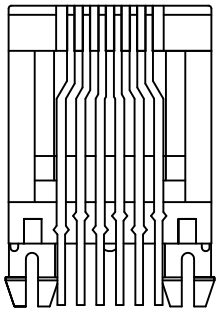
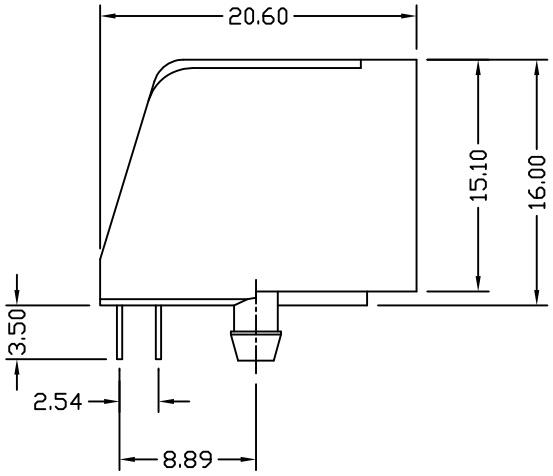
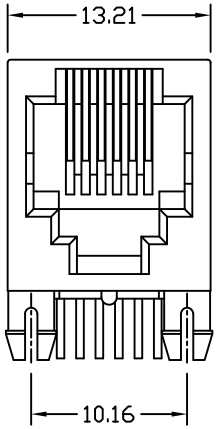
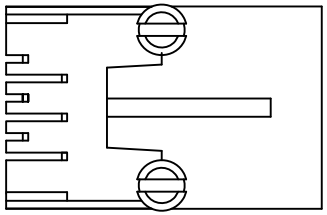
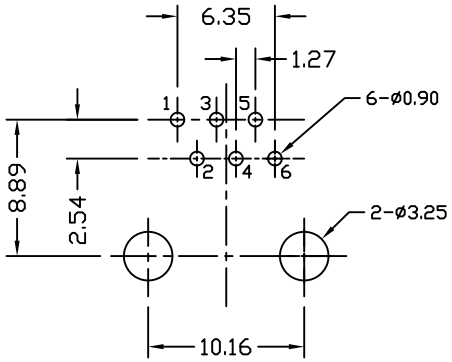
REV.	LOCAS.	DESCRIPTION	DATE	DRAWN
A		NEW	28.09.1988	LILY
B		P/N MJS-166-S157-9x -> MJS-166-R1M0-9x	02.12.2008	RONNY
C		New DWG. No.	01.02.2012	RONNY











RECOMMENDED HOLE PATTERN

RoHS 2002/95/EC compliant

NOTE

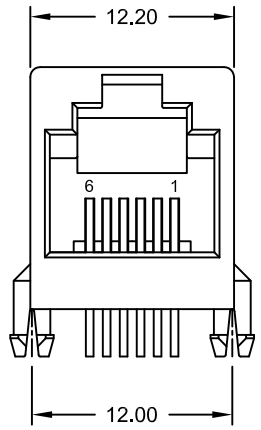
1. Material:
   Housing: PBT black UL 94V-0
   Contact: 0.35mm PhBz
   Plating: Sn over Ni on solder area
   Au over Ni on mating area
2. CAVITY CONFIRMS TO FCC RULES AND REGISTRATION PAR68, SUBPARTS F

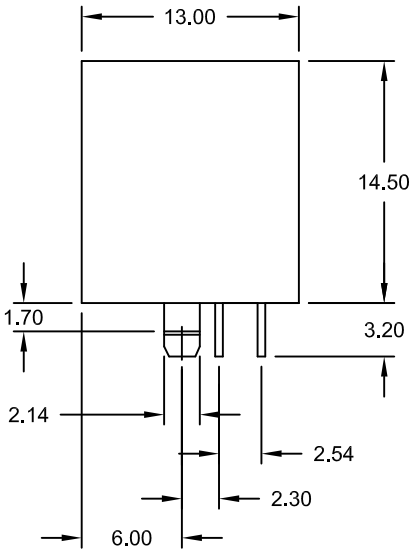
PART NUMBER	GOLD PLATING CONTACT AREA
MJS-166-R1M0-96	6μ"
MJS-166-R1M0-97	15μ"
MJS-166-R1M0-98	30μ"
MJS-166-R1M0-9H	50μ"

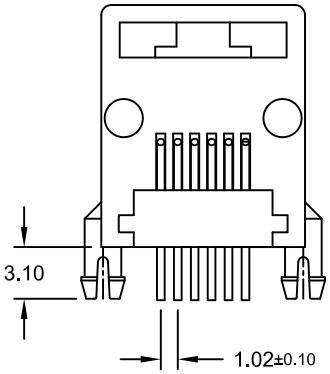
E-tec Interconnect

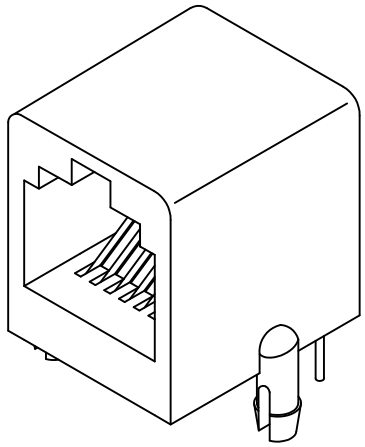
UNIT mm	GENERAL TOLERANCE		DRAWN LILY	DATE 28.09.1988	DWG. NO. 1311300	SHEET 1/1	RJ12 PCB Jack <6P6C> side entry NON shielded without panel stop
SCALE Free	X.° ±	X ± 0.50	CHECK Ronny	DATE 01.02.2012		REV. C	
	.X° ±	.X ± 0.38			SERIES NO. MJS-1xx-R1M0-9x		
	.XX° ±	.XX ± 0.25	APPROVE HOGI	DATE 01.02.2012			
	ANG ± 3°	.XXX ± 0.10					

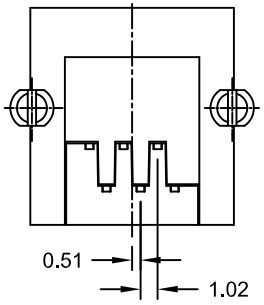
REV.	DESCRIPTION	DATE	DRAWN
A0	NEW	16.07.2003	RH
A2	dim 13.10 -> 13.00	20.07.2006	Gi
B	Correction dim. & plating	16.07.2007	Jack
C	change P/N: -RL155-9x/B -> -S1S0-9x & update	02.05.2013	Ronny
D	update	08.04.2015	Ronny

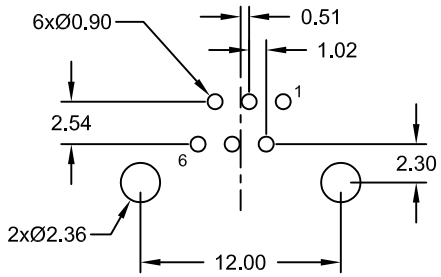












Recommended PCB Layout
(Top View)

PART NUMBER	GOLD PLATING CONTACT AREA
MJS-166-S1S0-96	6µ"
MJS-166-S1S0-97	15µ"
MJS-166-S1S0-98	30µ"
MJS-166-S1S0-9H	50µ"

RoHS compliant

Specifications

Electrical

Current rating: 1.5A
Insulation resistance: 500MΩ min. / 500V DC
Voltage rating: 125V AC max.
Withstanding voltage: 1000V rms 60Hz / Minute
Contact resistance: 30mΩ max. / 20mV DC

Material

Stamped pin 0.35 x 0.46mm Phosphor Bronze
Plating: Gold over Nickel on contact area,
Tin over Nickel on solder area.
Insulator: PBT UL 94V-0 (Black)

Operating temperature: -40°C to +70°C

Durability: 750 cycles min.
Cavity comply with FCC Rules and Regulations Part 68, Subpart F

E-tec Interconnect

UNIT	mm
SCALE	Free

GENERAL TOLERANCE	
X.° ±	X. ±
.X° ±	.X ±
.XX° ±	.XX ± 0.25
ANG ±	.XXX ±

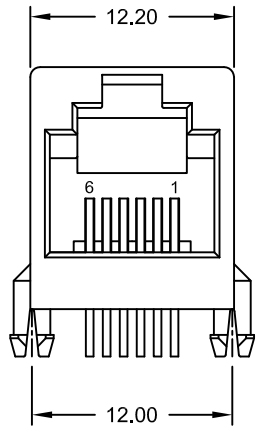
DRAWN	RH	16.07.2003
CHECK	Ronny	08.04.2015
APPROVE	Hogi	08.04.2015

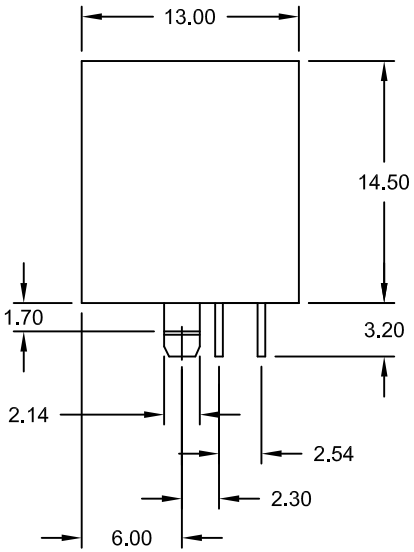
DWG. NO. 1311304 SHEET 1/1 REV. D
SERIES NO. MJS-166-S1S0-9x

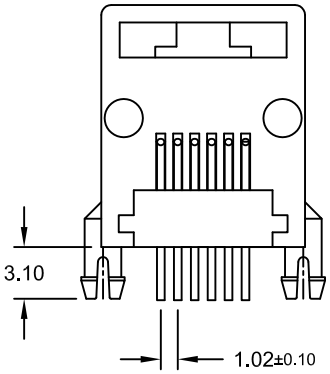
THT Side Entry PCB Jack

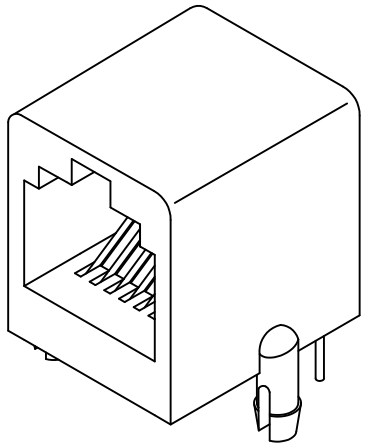
RJ12 <6P6C> short profile
without Panel Stop NON shielded
Black Colour

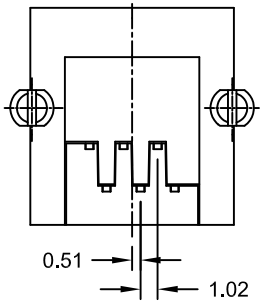
REV.	DESCRIPTION	DATE	DRAWN
A0	NEW	16.07.2003	RH
B	change P/N: -RL155-9x/G -> -S1S0-9x/G & update	02.05.2013	Ronny
C	update	07.04.2015	Ronny

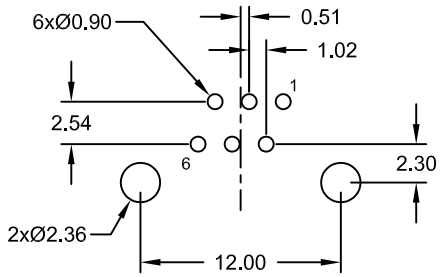












Recommended PCB Layout
(Top View)

PART NUMBER	GOLD PLATING CONTACT AREA
MJS-166-S1S0-96/G	6µ"
MJS-166-S1S0-97/G	15µ"
MJS-166-S1S0-98/G	30µ"
MJS-166-S1S0-9H/G	50µ"

RoHS compliant

Specifications

Electrical

Current rating: 1.5A
Insulation resistance: 500MΩ min. / 500V DC
Voltage rating: 125V AC max.
Withstanding voltage: 1000V rms 60Hz / Minute
Contact resistance: 30mΩ max. / 20mV DC

Material

Stamped pin 0.35 x 0.46mm Phosphor Bronze
Plating: Gold over Nickel on contact area,
Tin over Nickel on solder area.
Insulator: PBT UL 94V-0 (Gray)

Operating temperature: -40°C to +70°C

Durability: 750 cycles min.
Cavity comply with FCC Rules and Regulations Part 68, Subpart F

E-tec Interconnect

UNIT	mm
SCALE	Free

GENERAL TOLERANCE	
X.° ±	X. ±
.X° ±	.X ±
.XX° ±	.XX ± 0.25
ANG ±	.XXX ±

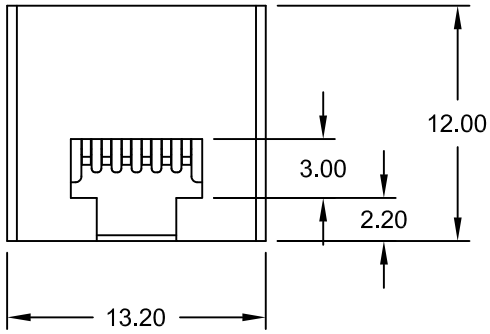
DRAWN	RH	16.07.2003
CHECK	Ronny	07.04.2015
APPROVE	Hogi	07.04.2015

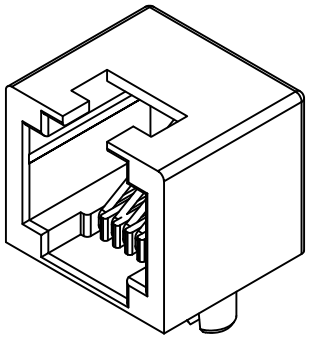
DWG. NO. 1311305 SHEET 1/1 REV. C
SERIES NO. MJS-166-S1S0-9x

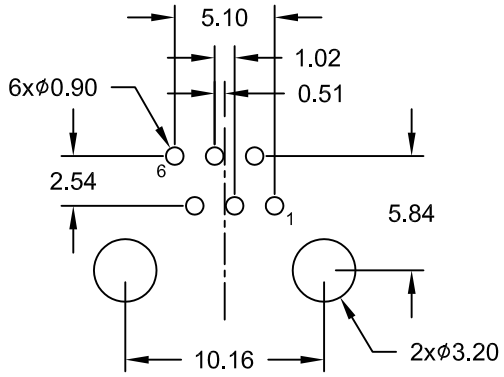
THT Side Entry PCB Jack

RJ12 <6P6C> short profile
without Panel Stop NON shielded
Gray Colour

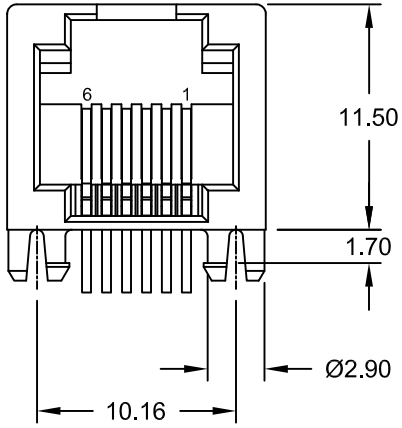
REV.	DESCRIPTION	DATE	DRAWN
A	NEW	26.05.2014	Ryan

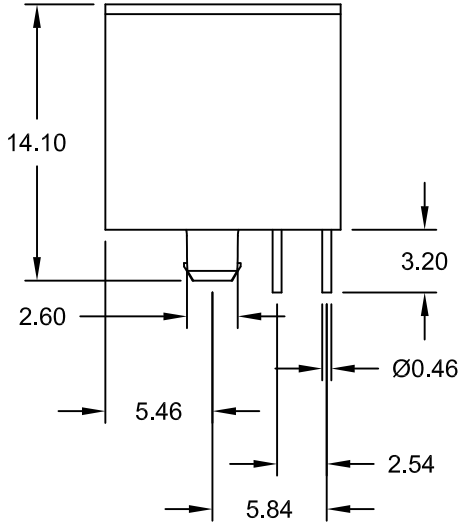






Recommended PCB Layout
Top View
(Tolerance ±0.05)





PART NUMBER	GOLD PLATING CONTACT AREA
MJS-166-S1S2-96	6µ"
MJS-166-S1S2-97	15µ"
MJS-166-S1S2-98	30µ"
MJS-166-S1S2-9H	50µ"

RoHS compliant

Specifications

Electrical

Current rating: 1.5A
Insulation resistance: 1000MΩ min. @ 500V DC
Voltage rating: 125V AC RMS
Withstanding voltage: 1000V RMS 60Hz/Minute
Contact resistance: 40mΩ max.

Material

Contact: Phosphor Bronze DIA.=0.46mm
Plating: Sn/Au over Ni
Shield: Brass
Plating: Ni
Insulator: PBT (black) UL 94V-0

Operating temperature: -20°C to +75°C
Storage temperature: -40°C to +85°C

Cavity confirms to FCC Rules and
Registration PAR 68, Subpart F

E-tec Interconnect

UNIT	mm
SCALE	Free

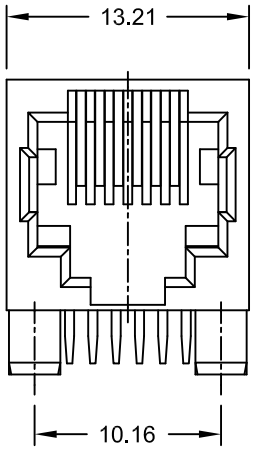
GENERAL TOLERANCE	
X.° ±	X. ±
.X° ±	.X ± 0.38
.XX° ±	.XX ± 0.25
.XXX° ±	.XXX ±

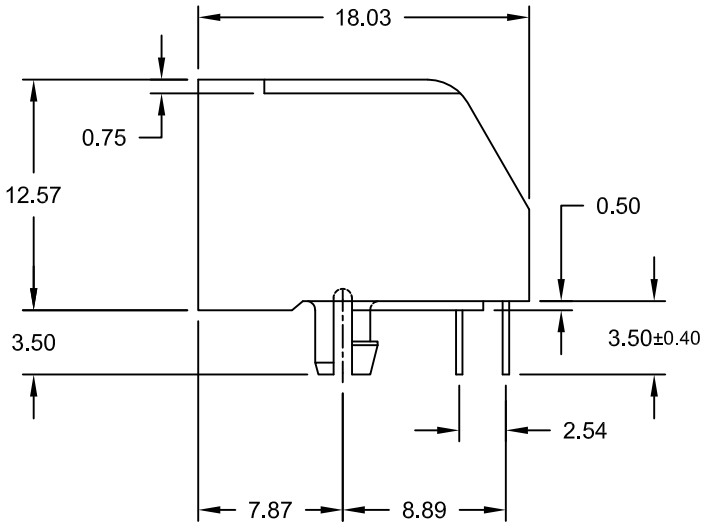
DRAWN	Ryan	DATE 26.05.2014
CHECK	Ronny	DATE 26.05.2014
APPROVE	Hogi	DATE 26.05.2014

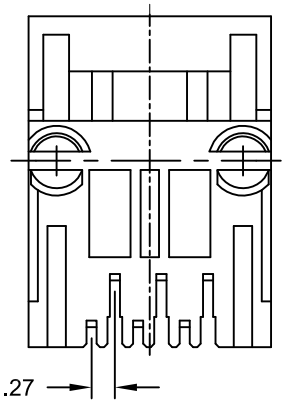
DWG. NO. 1311306
SHEET 1/1
REV. A
SERIES NO. MJS-166-S1S2-9x

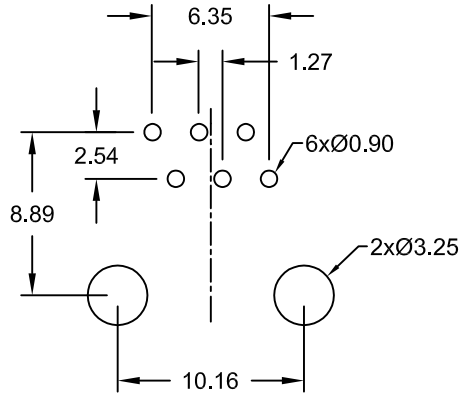
Side Entry RJ12 PCB Jack
<6P6C> short profile
non shielded - with round contacts

REV.	DESCRIPTION	DATE	DRAWN
A	Release	23.11.2009	Ryan Chou
B	update	27.05.2014	Ronny









Recommended PCB Layout
(Top View)

PART NUMBER	GOLD PLATING CONTACT AREA
MJS-166-S1S1-96	6μ"
MJS-166-S1S1-97	15μ"
MJS-166-S1S1-98	30μ"
MJS-166-S1S1-9H	50μ"

RoHS compliant

Specifications

Electrical

Current rating: 1.5A
Insulation resistance: 500MΩ min./500V DC
Withstanding voltage: 1000V rms 60Hz/Minute
Contact resistance: 40mΩ max./20mV DC

Material

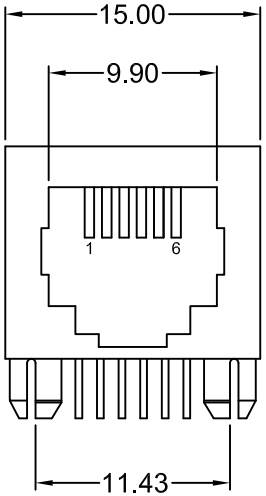
Contact: Phosphor Bronze
Plating: Sn on solder area;
Au flash on contact area
Insulator: PBT (Black) UL 94V-0

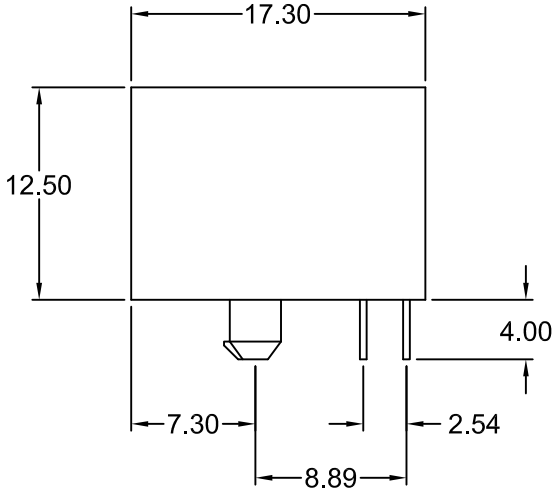
Operating temperature: -40°C to +105°C

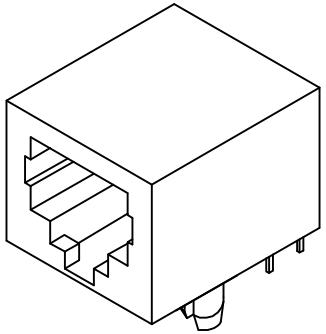
E-tec Interconnect

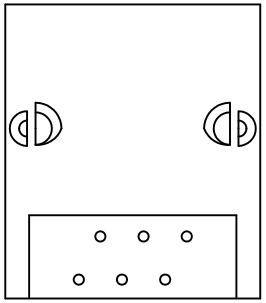
UNIT mm	GENERAL TOLERANCE		DRAWN Ryan Chou	DATE 23.11.2009	DWG. NO. 1311307	SHEET 1/1	Side Entry RJ12 PCB Jack <6P6C> short profile non shielded
SCALE Free	X.° ± 3°	X. ±	CHECK Ronny	DATE 27.05.2014		REV. B	
	.X° ±	.X ±	APPROVE Hogi	DATE 27.05.2014	SERIES NO. MJS-166-S1S1-9x		
	.XX° ±	.XX ± 0.25					
	.XXX° ±	.XXX ±					

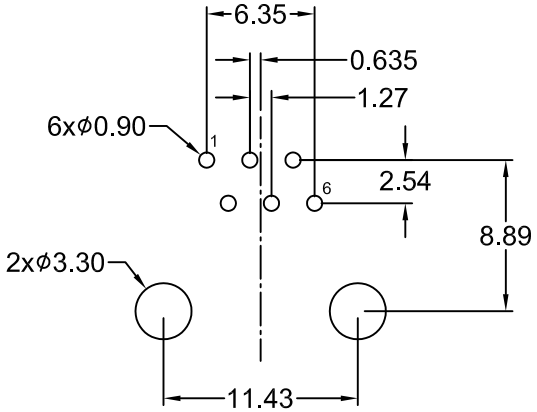
REV.	DESCRIPTION	DATE	DRAWN
A	NEW	17.02.2015	Ryan











Recommended PCB Hole Layout
(Top View)

PART NUMBER	GOLD PLATING CONTACT AREA
MJS-166-D4S0-96	6µ"
MJS-166-D4S0-97	15µ"
MJS-166-D4S0-98	30µ"
MJS-166-D4S0-9H	50µ"

RoHS compliant

Specifications

Electrical

Current rating: 1.5A
Insulation resistance: 500MΩ min. / 500V DC
Withstanding voltage: 1000V AC rms. 60 / Minuten
Contact resistance: 40mΩ max. / 20mV DC

Material

Contact: Phosphor Bronze t=0.35mm
Plating: Sn on solder area;
Au flash on contact area
Insulator: PBT (black) UL 94V-0

Operating temperature: -40°C to +105°C

Cavity comply with FCC Rules and Regulations Part 68, Subpart F

E-tec Interconnect

UNIT	mm
SCALE	Free

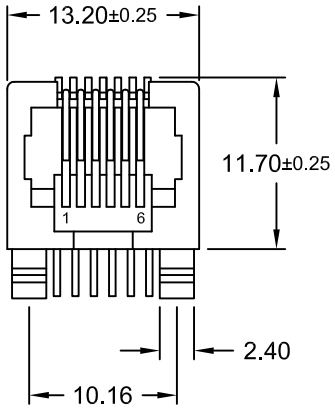
GENERAL TOLERANCE	
X.° ±	X. ±
.X° ±	.X ±
.XX° ±	.XX ± 0.25
ANG ±	.XXX ±

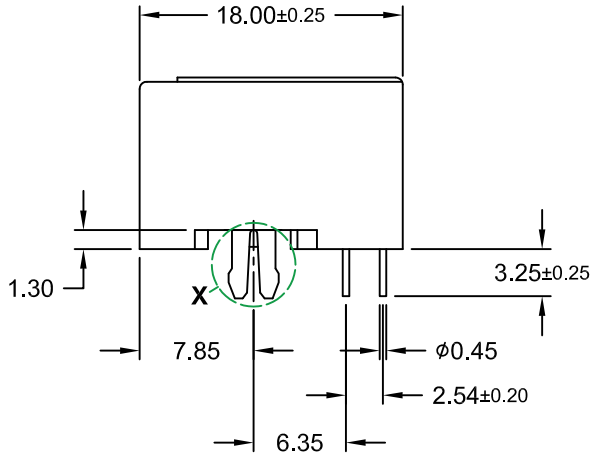
DRAWN	Ryan	DATE 17.02.2015
CHECK	Ronny	DATE 17.02.2015
APPROVE	Hogi	DATE 17.02.2015

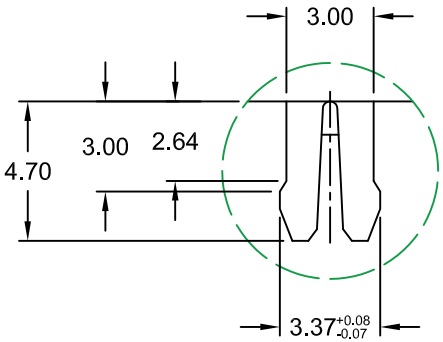
DWG. NO. 1311308
SHEET 1/1
REV. A
SERIES NO. MJS-166-D4S0-9x

Side entry PCB JACK
RJ12 <6P6C> "TAB down"
short profile Type
NON SHIELDED

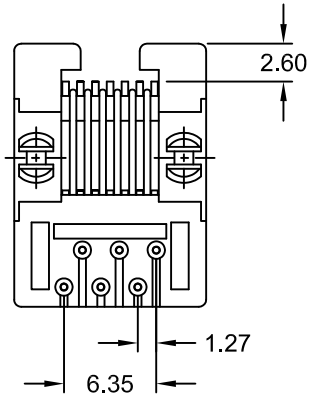
REV.	DESCRIPTION	DATE	DRAWN
A	New	28.06.2016	Cherry

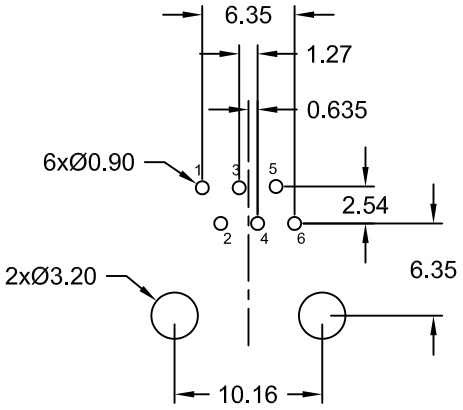






Detail X





Recommended PCB Layout
Top View
(Tolerance ±0.05)

PART NUMBER	GOLD PLATING CONTACT AREA
MJS-166-D3S0-55	flash
MJS-166-D3S0-56	6µ"
MJS-166-D3S0-57	15µ"
MJS-166-D3S0-58	30µ"
MJS-166-D3S0-5H	50µ"

Specifications

Electrical

Current rating: 1.5A
Insulation resistance: 500MΩ min.
Contact resistance: 30mΩ max.
Voltage rating: 150V AC max.
Withstanding voltage: 1000V AC / Minute

Material

Contact: Phosphor Bonze Ø0.45mm
Plating: Au flash on solder area,
Au on contact area (see PN code)
Insulator: Nylon46 (black) UL 94V-0

Operating temperature: -40°C to +85°C

Operating life: 750 cycles min.

Cavity comply with FCC Rules and Regulations Part 68, Subpart F

RoHS compliant

E-tec Interconnect

UNIT	mm
SCALE	Free

GENERAL TOLERANCE	
X.° ±	X. ±
.X° ±	.X ±
.XX° ±	.XX ± 0.13
.XXX° ±	.XXX ±

DRAWN	Cherry	DATE 28.06.2016
CHECK	Ronny	DATE 28.06.2016
APPROVE	Hogi	DATE 28.06.2016

DWG. NO. 1311309 SHEET 1/1 REV. A

SERIES NO. MJS-166-D3S0-xx

THT Side Entry PCB Jack

RJ12 <6P6C> "Tab down"
short profile Type
NON shielded